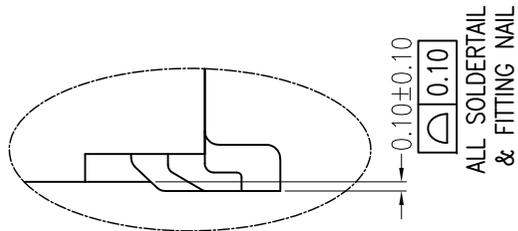
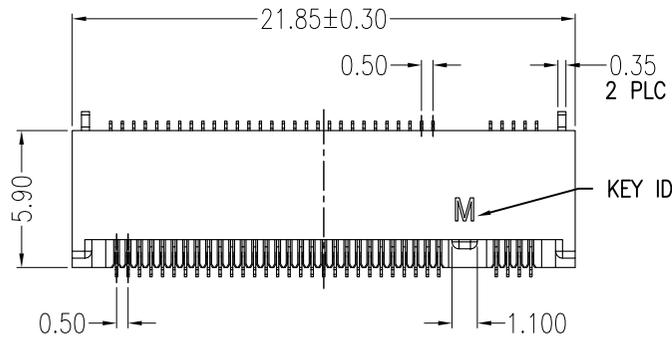
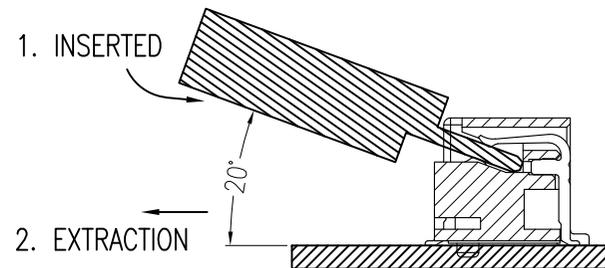


GP Component

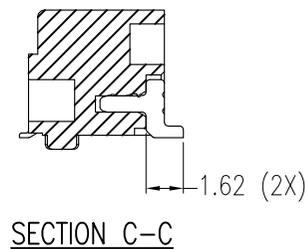
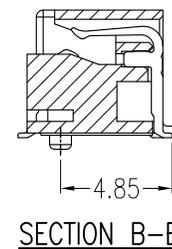
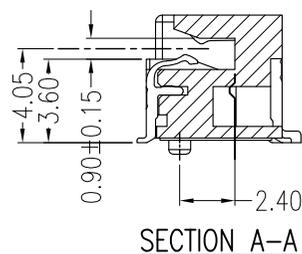
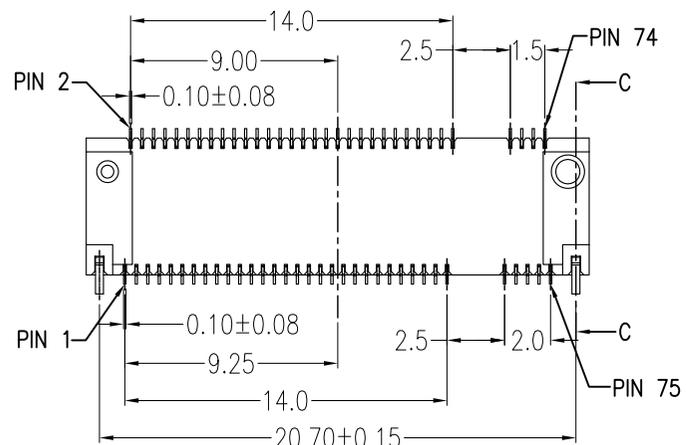
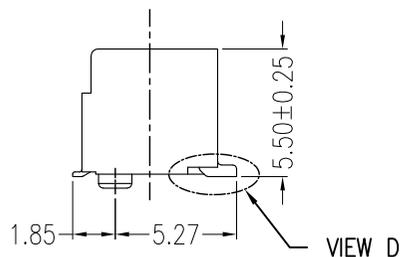
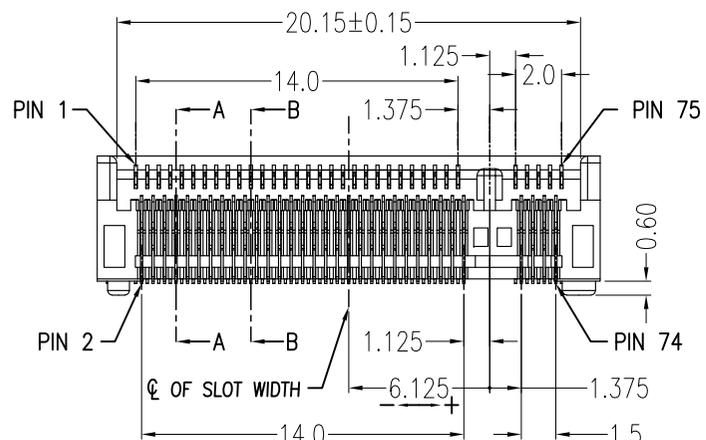
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2023/03/20	Ken Lin



VIEW D
SCALE 4:1



RECOMMENDED OPERATING FLOW:
MATE: 1
UNMATE: 2

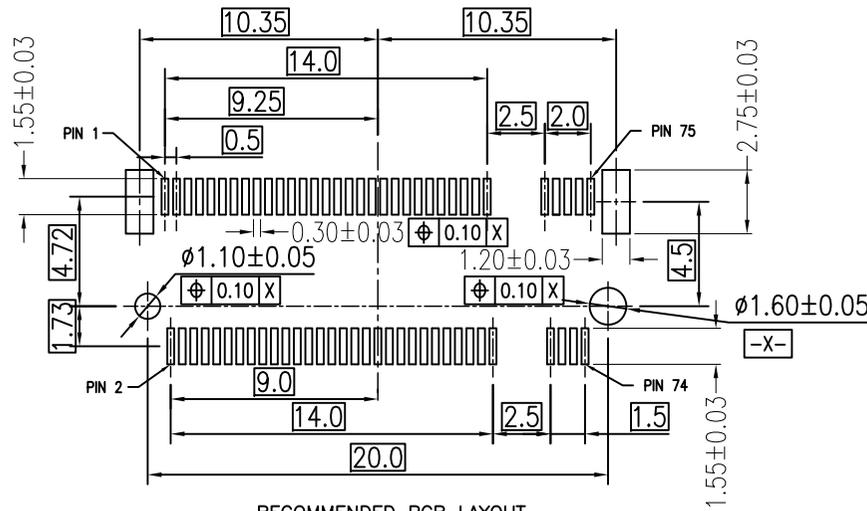
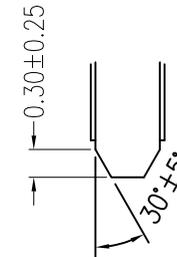
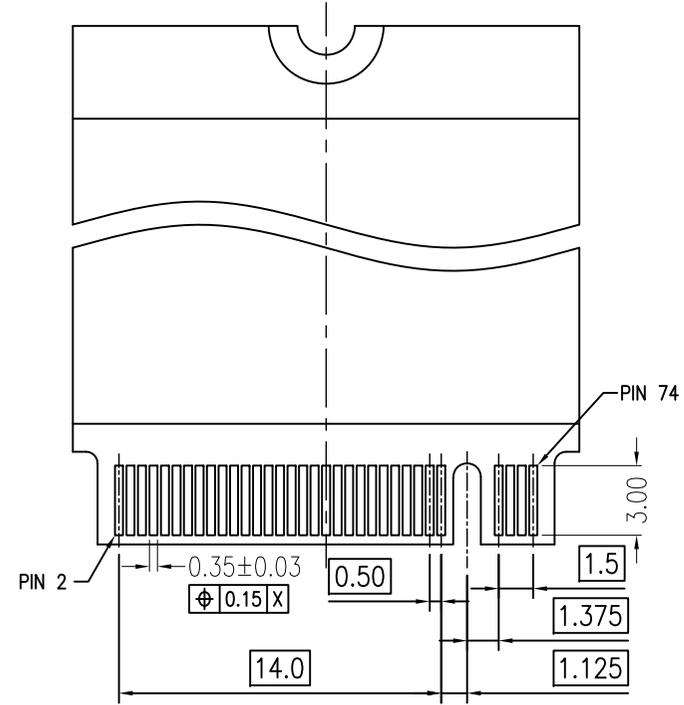
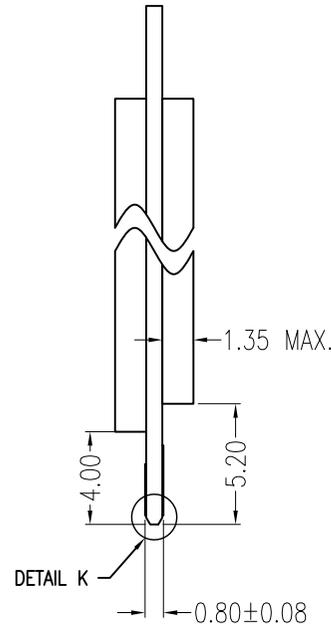
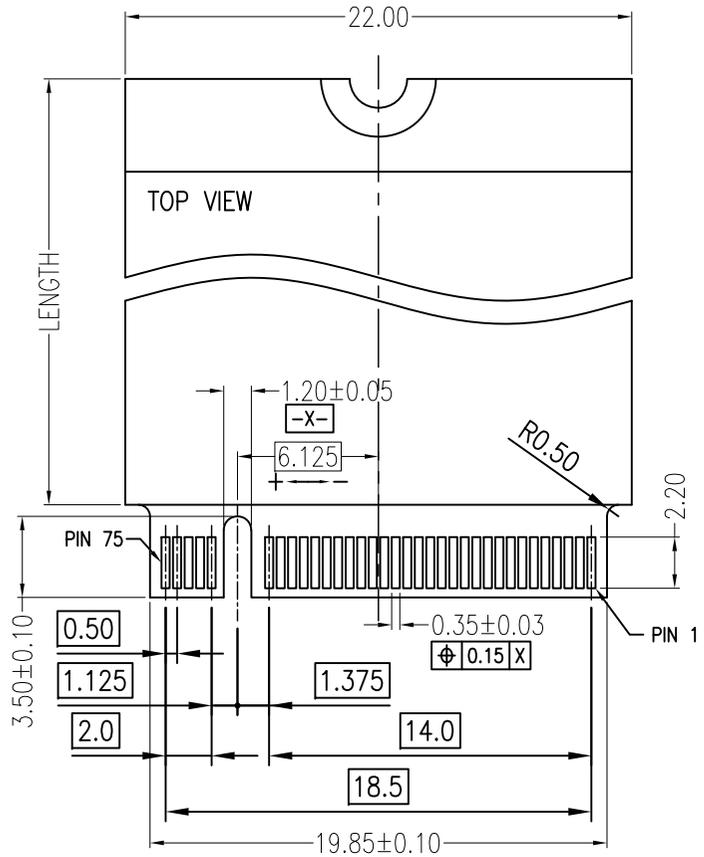


Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.50 X:XX ±0.30 X:XXX ±0.20 X:XXX ±0.15 ANGLE: ±5°	DESIGN BY :	DATE :	PART NAME:	
	Ken Lin	2023/03/20	NGFF M Key Connector Assembly H:5.50mm	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY:	DATE :	PART NO.	MNGFF-M-55-01-29-RS
	Hanson Huang	2023/03/20		
	APPROVED BY1:	DATE :	MOLD NO.	NA
	Richard Hsieh	2023/03/20		
	APPROVED BY2:	DATE :	DRAW NO.	
	Richard Hsieh	2023/03/20	SHEET NO.	1 OF 3

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2023/03/20	Ken Lin



Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.50 X:XX ±0.30 X:XXX ±0.20 X:XXX ±0.15 ANGLE: ±5°	DESIGN BY : Ken Lin	DATE : 2023/03/20	PART NAME: NGFF M Key Connector Assembly H:5.50mm	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Hanson Huang	DATE : 2023/03/20	PART NO.	MNGFF-M-55-01-29-RS
	APPROVED BY1: Richard Hsieh	DATE : 2023/03/20	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2023/03/20	DRAW NO.	
			SHEET NO.	2 OF 3

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2023/03/20	Ken Lin

NOTES:

*MATERIAL:

HOUSING: THERMOPLASTIC, HIGH TEMPERATURE LCP UL94 V-0, COLOR: BLACK.
 CONTACT: COPPER ALLOY.
 FITTING NAIL: COPPER ALLOY.

*FINISH:

CONTACT
 [SEE TABLE] GOLD PLATING ON THE CONTACT AREA.
 GOLD FLASH (0.8u" Min) PLATING ON THE SOLDERING AREA.
 1.27um~2.54um [50u"~100u"] MIN. NICKEL UNDERPLATING OVERALL.
 FITTING NAIL
 2.54um~5.08um [100u"~200u"] MIN. MATTE-TIN PLATING ON THE SOLDERING AREA.
 1.27um~2.54um [50u"~100u"] MIN. NICKEL UNDERPLATING OVERALL.

*Mechanical

Mating Force: 2.55 Kgf Max.
 Durability: 60 cycles 15u" & 30u" Au plating;
 25 cycles gold flash (0.8u" Min) plating.

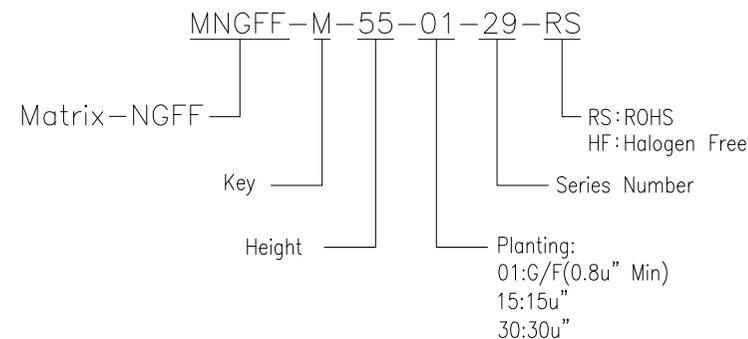
*Electrical Specification

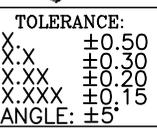
Current Rating: 50V AC 0.5A(Per pin).
 LLCR: 55mΩ Max,(Initial), 20mΩ Max. change.
 Insulation Resistance: 500MΩ Min. AT 500V DC.

*Environmental

Operating Temperature: -40°C ~ 85°C.
 Resistance to heat: the temperature shall be 260°C±5°C, 10 seconds Max.

ORDER INFORMATION :



Matrix Electronics Co.,Ltd				
 <p>TOLERANCE: X:X ±0.50 X:XX ±0.30 X:XXX ±0.20 X:XXX ±0.15 ANGLE: ±5</p>		DESIGN BY : Ken Lin	DATE : 2023/03/20	PART NAME: MNGFF M Key Connector Assembly H:5.50mm
 <p>UNIT: mm [inch]</p>		CHECKED BY: Hanson Huang	DATE : 2023/03/20	PART NO. MNGFF-M-55-01-29-RS
 <p>SCALE:1:1 SIZE:A4</p>		APPROVED BY1: Richard Hsieh	DATE : 2023/03/20	MOLD NO. NA
		APPROVED BY2: Richard Hsieh	DATE : 2023/03/20	DRAW NO.
				SHEET NO. 3 OF 3